

MAX5825PMB1 Peripheral Module

General Description

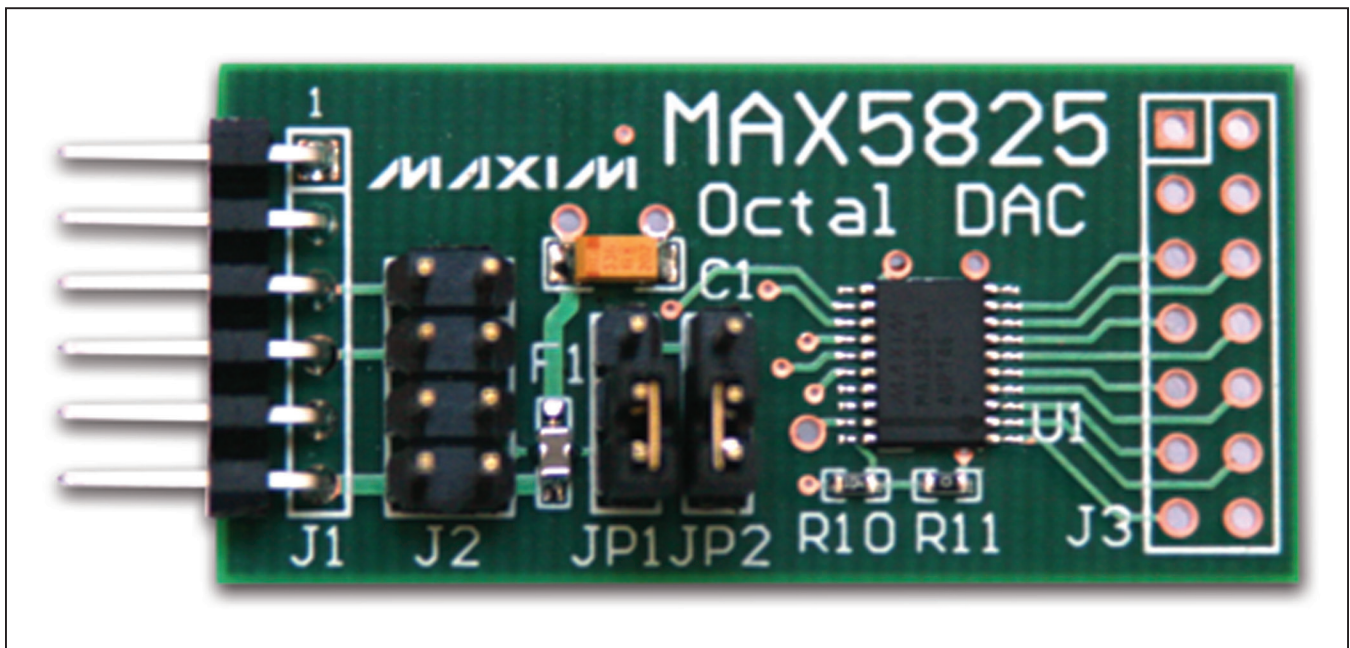
The MAX5825PMB1 peripheral module provides the necessary hardware to interface the MAX5825 8-channel DAC to any system that utilizes Pmod™-compatible expansion ports configurable for I²C communication. The IC features eight independent 12-bit accurate internally buffered voltage-output DAC channels. The IC also features an internal reference that is selectable between 2.048V, 2.500V, and 4.096V (4.096V reference operation is not supported with a standard 3.3V Pmod-port power supply).

Features

- ◆ Eight High-Accuracy DAC Channels
- ◆ 12-Bit Accuracy without Adjustment
- ◆ Precision Voltage Reference Internal to the IC
- ◆ Provision for Optional External Reference Input
- ◆ Jumper-Selectable I²C Address Setting
- ◆ 6-Pin Pmod-Compatible Connector (I²C)
- ◆ Secondary Header Allows Daisy-Chaining of Additional Modules on the I²C Bus
- ◆ Example Software Written in C for Portability
- ◆ RoHS Compliant
- ◆ Proven PCB Layout
- ◆ Fully Assembled and Tested

[Ordering Information](#) appears at end of data sheet.

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Component List

DESIGNATION	QTY	DESCRIPTION
C1	1	10 μ F \pm 10%, 10V X5R ceramic capacitor (0603) TDK C2012X5R1A106K/1.25
C2	1	2.2 μ F \pm 10%, 10V X5R ceramic capacitor (0603) TDK C1608X5R1A225K/0.80
C3, C4	2	0.1 μ F \pm 10%, 16V X7R ceramic capacitors (0603) Murata GRM188R71C104KA01D
F1	1	4.7 μ F EMI filter (3-terminal capacitor) Murata NFM21PC475B1A3D
J1	1	6-pin right-angle male header

DESIGNATION	QTY	DESCRIPTION
J2	1	8-pin (2 x 4) straight male header
J3	1	14-pin (2 x 7) straight male header
JP1, JP2	2	3-pin straight male headers
R1–R4	4	150 Ω \pm 5% resistors (0603)
R5–R9	5	4.7k Ω \pm 5% resistors (0603)
R10	0	Not installed, 100k Ω resistor (0603)
U1	1	Octal-channel, 12-bit buffered DAC (20 TSSOP) Maxim MAX5825AAUP+
—	2	Shorting jumpers
—	1	PCB: EPCB5825PM1

Component Suppliers

SUPPLIER	PHONE	WEBSITE
Murata Electronics North America, Inc.	770-436-1300	www.murata-northamerica.com
TDK Corp.	847-803-6100	www.component.tdk.com

Note: Indicate that you are using the MAX5825PMB1 when contacting these component suppliers.

Detailed Description

I²C Interface

The MAX5825PMB1 peripheral module can interface to the host in one of two ways. It can plug directly into a Pmod-compatible port (configured for I²C) through connector J1, or in this case, other I²C boards can attach to the same I²C bus through connector J2.

I²C Interface (Daisy-Chaining Modules)

Alternatively, the peripheral module can connect to other I²C-based Pmod modules using a 4-conductor ribbon cable connecting to the J2 connector. In this situation, pins 1-4 and 5-8 on J2 provide two connections to the I²C bus, allowing the module to be inserted into an I²C bus daisy-chain.

Connector J1 provides connection of the module to the Pmod host. The pin assignments and functions adhere to the Pmod standard recommended by Digilent. See Table 1.

The J2 connector allows the module to be connected through a daisy-chain from another I²C module and/or provide I²C and power connections to other I²C modules on the same bus. See Table 2.

Table 1. Connector J1 (I²C Communication)

PIN	SIGNAL	DESCRIPTION
1	$\overline{\text{LDAC}}$	Active-low asynchronous DAC load input
2	$\overline{\text{IRQ}}$	Active-low open-drain interrupt output. $\overline{\text{IRQ}}$ low indicates a watchdog timeout.
3	SCL	I ² C serial clock
4	SDA	I ² C serial data
5	GND	Ground
6	VDD	Power supply

Table 2. Connector J2 (I²C Expansion)

PIN	SIGNAL	DESCRIPTION
1	SCL	I ² C serial clock
2	SDA	I ² C serial data
3	GND	Ground
4	VDD	Power supply
5	SCL	2-wire serial clock. Same as pin 1 above.
6	SDA	2-wire serial data. Same as pin 2 above.
7	GND	Ground
8	VDD	Power supply

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I²C Addressing Options

The I²C slave address for the IC can be one of nine different values, depending on the settings on jumpers JP1 and JP2. Table 3 lists the settings of those jumpers and the corresponding values of the slave address A[3:0]. Refer to the MAX5823/MAX5824/MAX5825 IC data sheet for more information.

External Control Signals

The IC implements pins that allow asynchronously updating of all DAC channels simultaneously ($\overline{\text{LDAC}}$) and simultaneously clearing all DAC channels to their default state ($\overline{\text{CLR}}$). The $\overline{\text{CLR}}$ pin is only available through the external J3 connector. The $\overline{\text{LDAC}}$ signal is available from either the Pmod connector (J1) or the external connector (J3). The default source for $\overline{\text{LDAC}}$ is the Pmod connector (J1). To control $\overline{\text{LDAC}}$ from the external connector (J3), modify the solder link on the back of the board (labeled LK1). The user is cautioned to ensure that only one source for this signal is selected at any given time.

The J3 connector provides the DAC output voltages and the external control inputs. See Table 4.

Reset State (M/\overline{Z} Pin)

The IC features a pin-selectable DAC reset state using the M/\overline{Z} input. Upon a power-on reset, all CODE and DAC data registers are reset to zero scale ($M/\overline{Z} = \text{GND}$) or midscale ($M/\overline{Z} = \text{VDD}$). The board is shipped with R11 installed (0Ω) and R10 not installed, which sets M/\overline{Z} to GND. To change to $M/\overline{Z} = \text{VDD}$, remove R11 and install a suitable pullup resistor for R10. Refer to the MAX5823/MAX5824/MAX5825 IC data sheet for more information.

Table 3. I²C Slave Address LSBs

JP1 (ADDR1)	JP2 (ADDR0)	A3	A2	A1	A0
1-2 (VDD)	1-2 (VDD)	1	1	1	1
1-2 (VDD)	Open	1	1	1	0
1-2 (VDD)	2-3 (GND)	1	1	0	0
Open	1-2 (VDD)	1	0	1	1
Open	Open	1	0	1	0
Open	2-3 (GND)	1	0	0	0
2-3 (GND)	1-2 (VDD)	0	0	1	1
2-3 (GND)	Open	0	0	1	0
2-3 (GND)	2-3 (GND)	0	0	0	0

Software and FPGA Code

Example software and drivers are available that execute directly without modification on several FPGA development boards that support an integrated or synthesized microprocessor. These boards include the Digilent Nexys 3, Avnet LX9, and Avnet ZEDBoard, although other platforms can be added over time. Maxim provides complete Xilinx ISE projects containing HDL, Platform Studio, and SDK projects. In addition, a synthesized bit stream, ready for FPGA download, is provided for the demonstration application.

The software project (for the SDK) contains several source files intended to accelerate customer evaluation and design. These include a base application (maximModules.c) that demonstrates module functionality and uses an API interface (maximDeviceSpecificUtilities.c) to set and access Maxim device functions within a specific module.

The source code is written in standard ANSI C format, and all API documentation including theory/operation, register description, and function prototypes are documented in the API interface file (maximDeviceSpecificUtilities.h & .c).

The complete software kit is available for download at www.maxim-ic.com. Quick start instructions are also available as a separate document.

Table 4. Connector J3 (External Interface)

PIN	SIGNAL	DESCRIPTION
1	VDD	Supply voltage
2	$\overline{\text{LDACEXT}}$	Active-low asynchronous DAC load input
3	GND	Ground
4	$\overline{\text{CLR}}$	Active-low asynchronous DAC clear input
5	DAC7	DAC channel 7 voltage output
6	DAC6	DAC channel 6 voltage output
7	DAC5	DAC channel 5 voltage output
8	DAC4	DAC channel 4 voltage output
9	DAC3	DAC channel 3 voltage output
10	DAC2	DAC channel 2 voltage output
11	DAC1	DAC channel 1 voltage output
12	DAC0	DAC channel 0 voltage output
13	REF	Reference voltage input/output
14	GND	Ground

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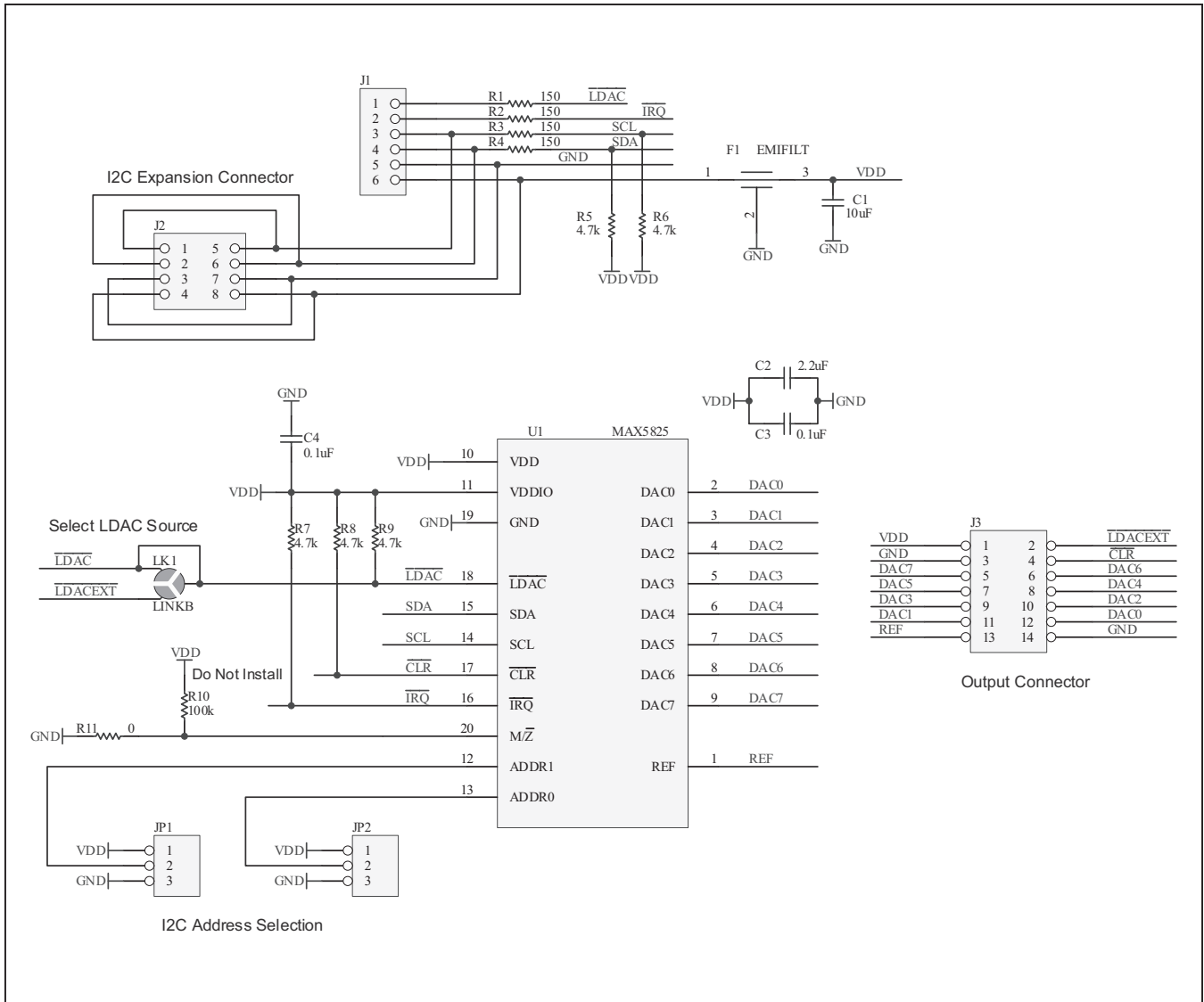


Figure 1. MAX5825PMB11 Peripheral Module Schematic

MAX5825PMB1 Peripheral Module

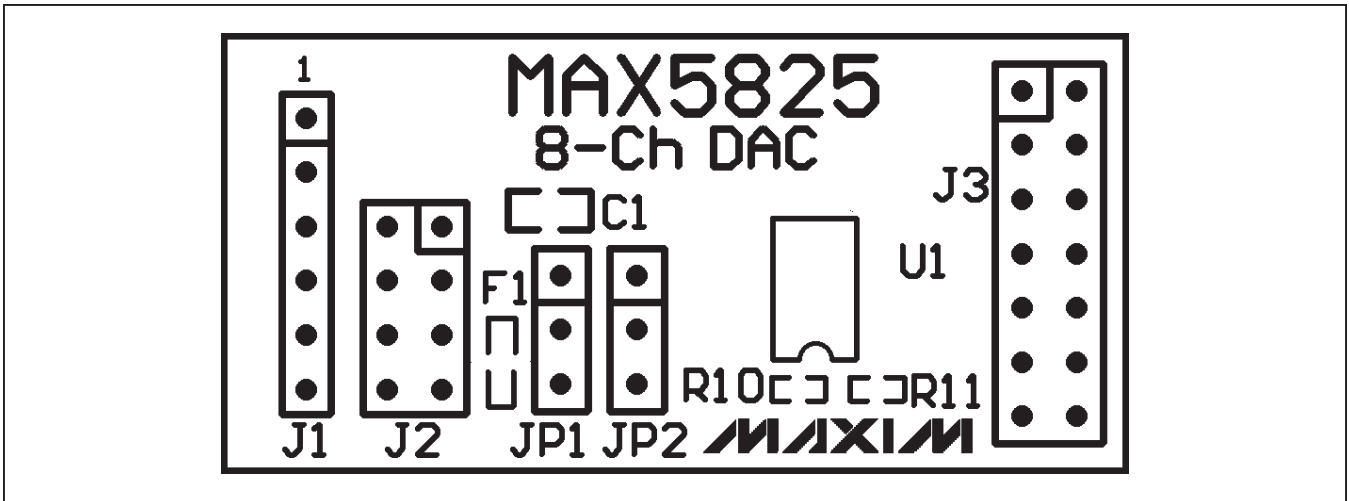


Figure 2. MAX5825PMB11 Peripheral Module Component Placement Guide—Component Side

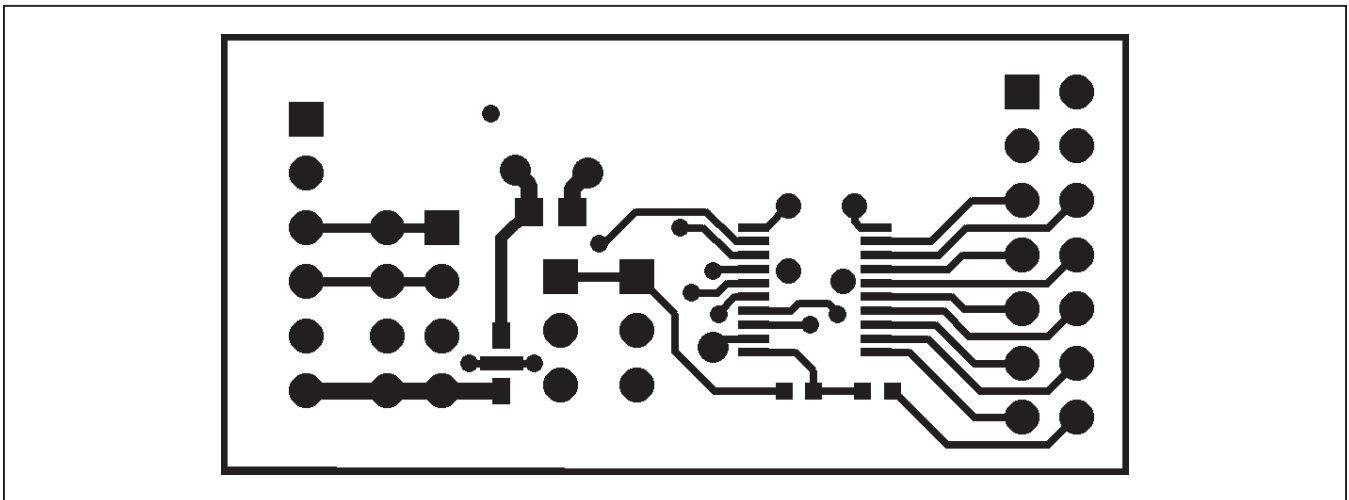


Figure 3. MAX5825PMB11 Peripheral Module PCB Layout—Component Side

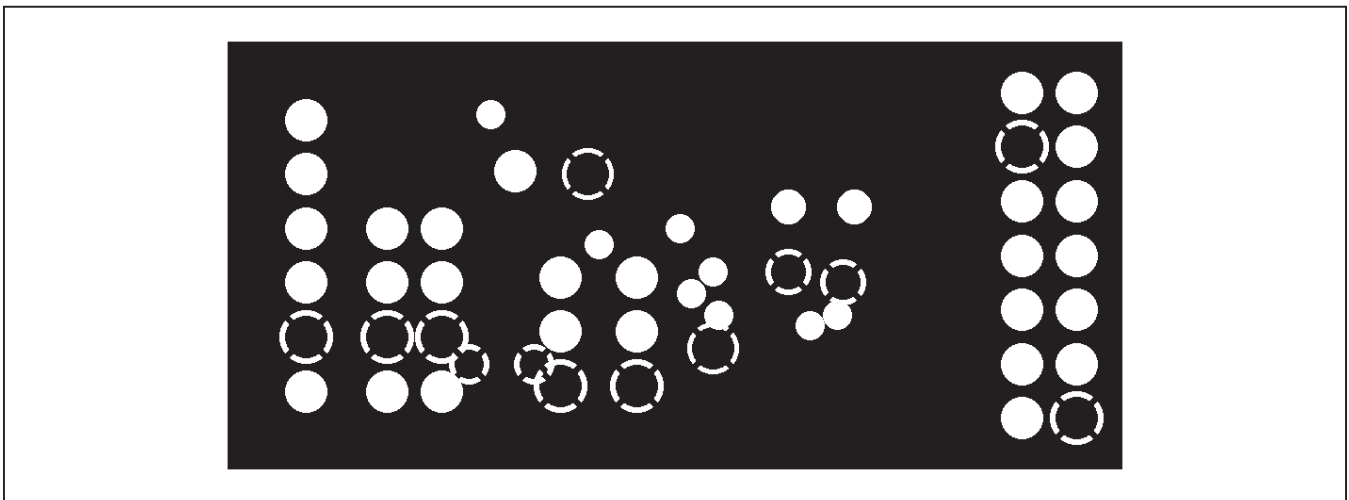


Figure 4. MAX5825PMB11 Peripheral Module PCB Layout—Inner Layer 1 (Ground)

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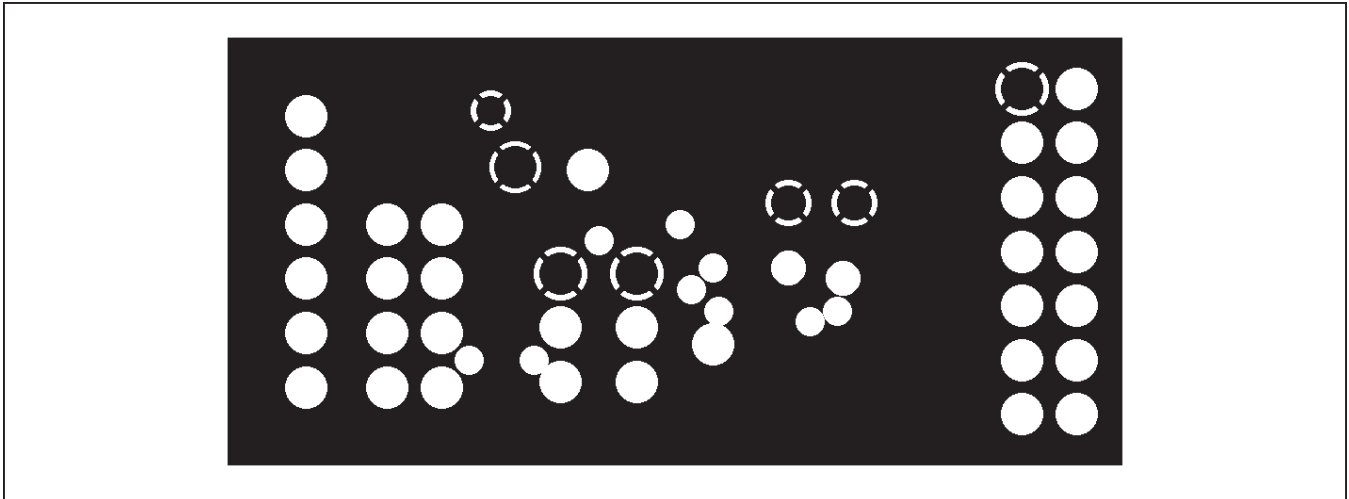


Figure 5. MAX5825PMB11 Peripheral Module PCB Layout—Inner Layer 2 (Power)

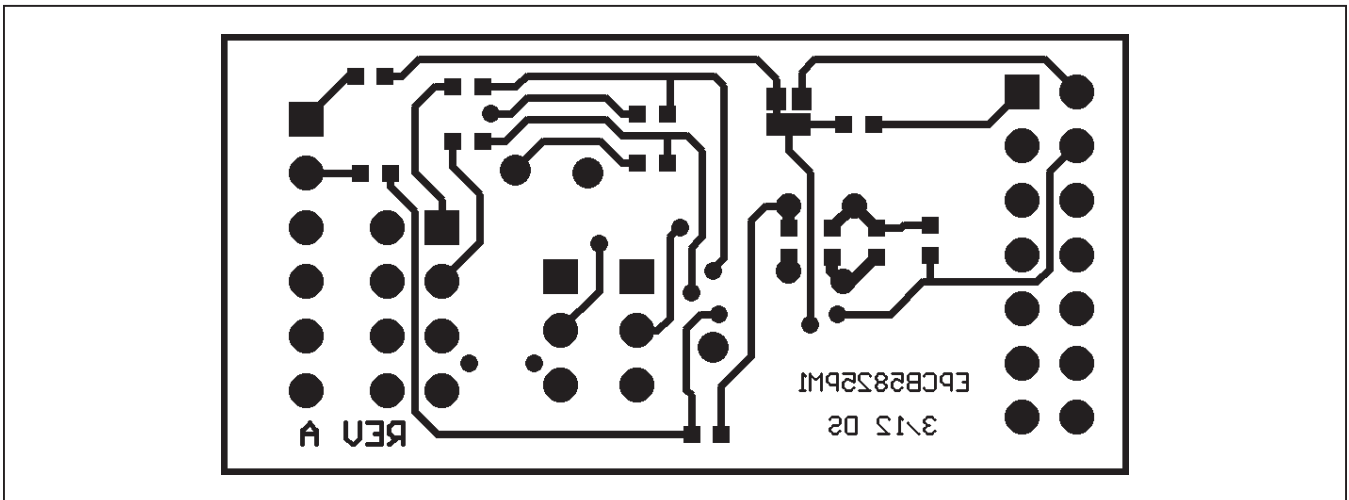


Figure 6. MAX5825PMB11 Peripheral Module PCB Layout—Solder Side

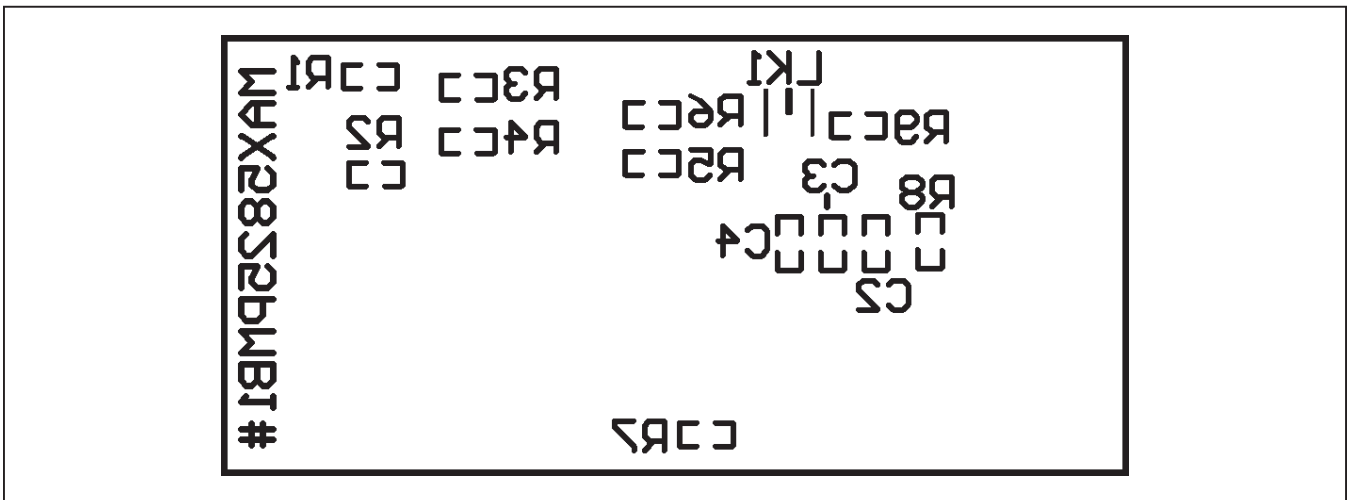


Figure 7. MAX5825PMB11 Peripheral Module Component Placement Guide—Solder Side

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Ordering Information

PART	TYPE
MAX5825PMB1#	Peripheral Module

#Denotes RoHS compliant.

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Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	5/12	Initial release	—

Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.

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